

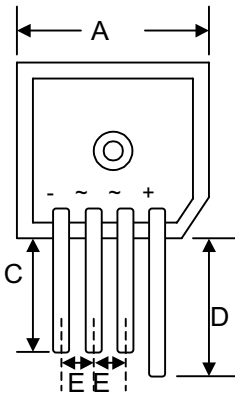
Data Sheet 1339 Rev.—

Features

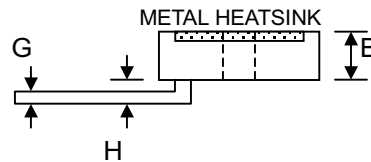
- Glass Passivated Die Construction
- Low Forward Voltage Drop
- High Current Capability
- High Reliability
- High Surge Current Capability
- Ideal for Printed Circuit Boards
- Designed for Saving Mounting Space

Mechanical Data

- Case: Epoxy Case with Heat Sink Internally Mounted in the Bridge Encapsulation
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Body
- Weight: 30 grams (approx.)
- Mounting Position: Any
- Marking: Type Number



KBPC-S		
Dim	Min	Max
A	28.40	28.70
B	10.97	11.23
C	13.90	—
D	19.10	—
E	5.10	—
G	1.20 Ø Typical	
H	3.05	3.60
All Dimensions in mm		



Maximum Ratings and Electrical Characteristics @ $T_A=25^\circ\text{C}$ unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristics		Symbol	-00GS	-01GS	-02GS	-04GS	-06GS	-08GS	-10GS	Unit	
Peak Repetitive Reverse Voltage		V_{RRM}								V	
Working Peak Reverse Voltage		V_{RWM}	50	100	200	400	600	800	1000	V	
DC Blocking Voltage		V_R								V	
RMS Reverse Voltage		$V_{R(RMS)}$	35	70	140	280	420	560	700	V	
Average Rectified Output Current	KBPC15	I_o	15								A
	KBPC25		25								
	KBPC35		35								
Non-Repetitive Peak Forward Surge Current, 8.3ms Single Half-sine-wave Superimposed on Rated Load (JEDEC Method)	KBPC15 KBPC25 KBPC35	I_{FSM}	300								A
			300								
			400								
Forward Voltage Drop (per element)	KBPC15 @ $I_F = 7.5A$ KBPC25 @ $I_F = 12.5A$ KBPC35 @ $I_F = 17.5A$	V_{FM}	1.1								V
Peak Reverse Current at Rated DC Blocking Voltage (per element)	@ $T_C = 25^\circ\text{C}$ @ $T_C = 125^\circ\text{C}$	I_R	5.0								μA
			500								
I^2t Rating for Fusing ($t < 8.3\text{ms}$) (Note 1)	KBPC15 KBPC25 KBPC35	I^2t	374								A^2s
			374								
			664								
Typical Thermal Resistance (per element) (Note 2)		$R_{\theta JC}$	2.0								K/W
RMS Isolation Voltage from Case to Lead		V_{iso}	2500								V
Operating and Storage Temperature Range		T_j, T_{STG}	-65 to +150								$^\circ\text{C}$

Note: 1. Non-repetitive for $t > 1\text{ms}$ and $< 8.3\text{ms}$.

2. Thermal resistance junction to case per element mounted on 220 x 220 x 50mm thick AL plate.

